# Hybrid 7p151 Traveler

April 12, 2000

## 1 Connectivity

Repairs on shorts:
Fixes for opens: HV+ fixed with soldered wire.

## 2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7P151 has die: 151-029 151-030 151-031 151-034 151-036 151-037 151-038

## 3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

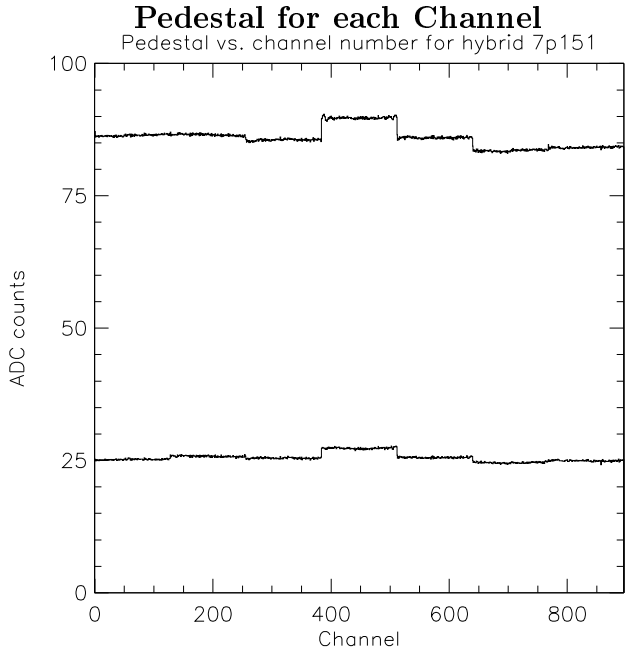
```
% Hybrid 7p151 classification info. Created 09:51:31 04/10/00

Hybrid 7p151 quality: fair
Chip classification: good good good good fair good good
Bad channels (chip-channel): 4-127
Bad cells: none
Random bad capacitors: none
Channels at pedestal needed for DCMS: 31.6 30.7 28.6 27.7 29.7 30.6 30.7
```

## 4 Comments

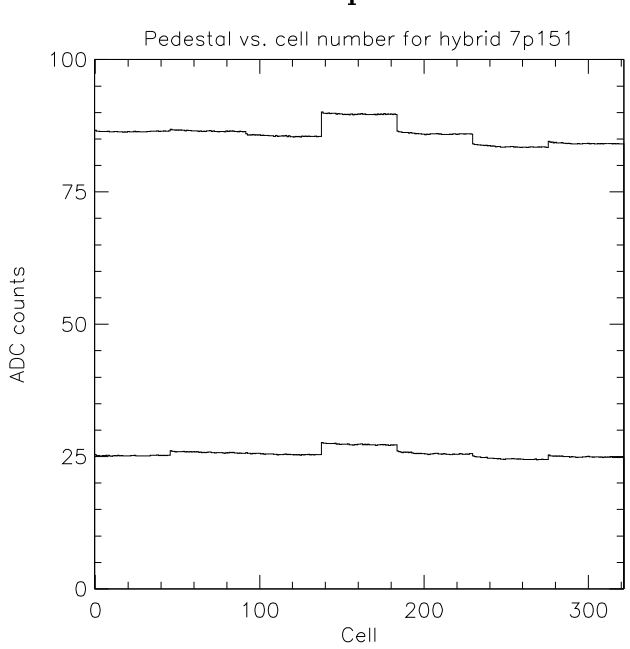
Encapsulated. FE DV finger gold bonds. HV tested.

# 5 Pedestal

The following plot shows the pedestals vs. channel number with and without charge injection:



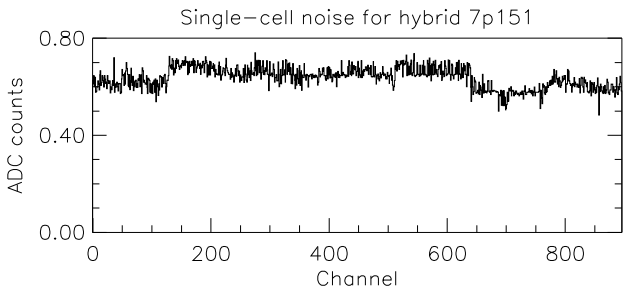

The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

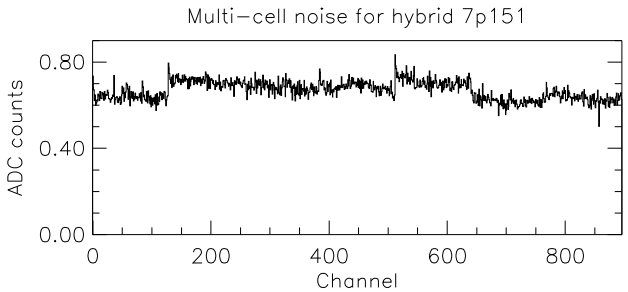


# 6 Noise

The following plots show the single-cell and multi-cell RMS noise:

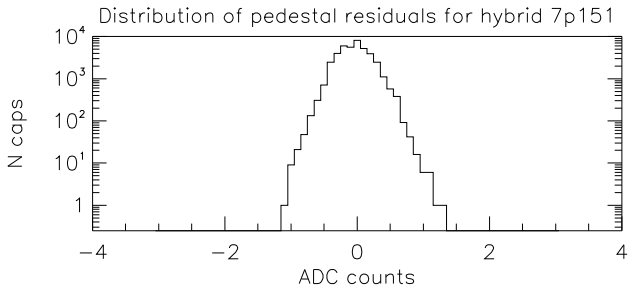
**RMS Noise**

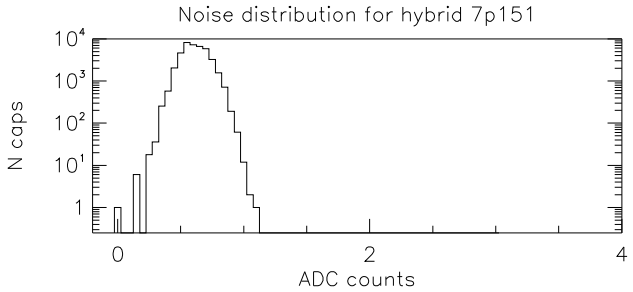


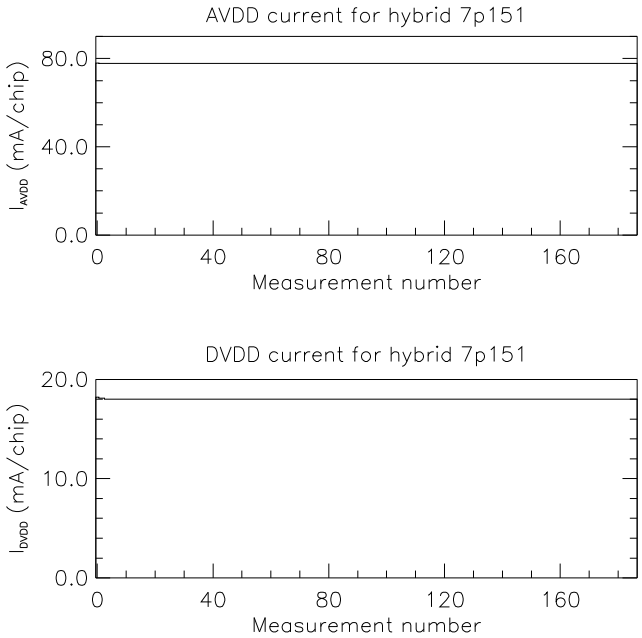

The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

**Distribution of Pedestals and Noise**



# 7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

**Supply Currents During Burn-in**